

Electronic Patent Application Fee Transmittal

Application Number:	10805890			
Filing Date:	22-Mar-2004			
Title of Invention:	Method of plasma etching of high-K dielectric materials with high selectivity to underlying layers			
First Named Inventor:	Padmapani C. Nallan			
Filer:	Keith Patrick Taboada			
Attorney Docket Number:	7017 C1/ETCH/METAL-NVM/JB			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Statutory disclaimer	1814	1	130	130
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130